



AOS NON-SILICONE HTC 100

NEW! Product Code: 52060



TECHNICAL DATA SHEET

Product Description

AOS 52060 is an easy spreading, low bond line thickness, non-silicone, metal-filled thermal grease. (For a non-silicone, low BLT material without metal particles see 52050) The material has no bleed, phase separate or pump out under typical applications, and will survive temperatures up to 200°C for brief periods.

Product Features and Benefits

AOS 52060 has no special storage requirements, has no volatile content, is non-reactive, and has excellent humidity resistance along with high thermal stability.

- As with our entire line of Heat Sink Compounds, the AOS technical staff can modify AOS 52060 to meet your requirements.
- AOS 52060 is available in syringes, cartridges, jars, and bulk packaging.

Typical Properties

<u>Property</u>	<u>Value</u>	<u>Test Method</u>
Consistency (Penetration, worked, 60x)	280 - 320	ASTM D-217
Specific Gravity, @ 25°C	2.6	ASTM D-70
Bleed, @ 200°C, 24 Hrs., %/Wt	0.3	FTM-321 MODIFIED
Evaporation, @ 200°C, 24 Hrs., %/Wt.	0.50	FTM-321 MODIFIED
Thermal Conductivity, @ 36°C W/m- K	6.0	ASTM D 5470-06
Thermal Resistance, @ 50 °C °C/W	0.0369	Oracle TTV model 270-7806-01
Anticipated Minimum Bond line (mils)	0.3	Determined @ 1, 2, 5 and 20 mil thicknesses
Based on Filler Dimensions	1	
Operating Temperature Range	-40°C to 200°C	
Flow Rate grams/min.	5-8	AOS Method #1
Appearance	Dark Gray Paste	

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